"SoC Technology Towards a New Era of Innovation"

ISOCC 2022
19th International SoC Design Conference

October 19(Wed.)~22(Sat.), 2022
Lakai Sandpine Resort,
Gangneung-si, Gangwon-do, Korea

CALL FOR PAPERS

ABOUT ISOCC

ISOCC has established a long tradition as an annual conference providing the premier SoC design forum for worldwide researchers from academia and industries. Since its inception, ISOCC has been continuing to showcase the most recent innovations and trends in the semiconductor system-on-a-chip area with active participations from worldwide researchers in academia, industry, and institutes. ISOCC 2022 welcomes technical papers in the field of semiconductor circuits and systems presenting new advanced concept and developments in analog and digital circuit and system design, theory, simulation, modeling, experimental implementations and experiences, and emerging technologies in the system-on-a-chip area.

The 19th International SoC Conference (ISOCC 2022) will be held from October 19 to 22, 2022 at Lakai Sandpine Resort, Gangneung-si, Gangwon-do in Korea. Gangneung, where ISOCC 2022 will be held, is a municipal city in the province of Gangwon-do, on the east coast of South Korea. Gangneung is the economic center of the Yeongdong region of Gangwon-do. Gangneung has many tourist attractions, such as Jeongdongjin, a very popular area for watching the sunrise, and Gyeongpo Beach. The city hosted all the ice events for the 2018 Winter Olympics. It takes two hours by KTX(Korea's high-speed train) from Seoul to reach Gangneung.

ISOCC 2022 is financially co-sponsored by IEEE CAS Society. All accepted papers will be published in the conference proceedings and will be submitted for inclusion in IEEE Xplore. We also welcome proposals for tutorials and special sessions.

TOPICS OF INTEREST
Topics include, but are not limited to:

- **Analog Circuits**
  - Analog Circuits
  - Amplifiers and Filters
  - Power Management Circuits
- **Data Converters**
  - Analog-to-Digital Converter
  - Digital-to-Analog Converters
  - Analog Circuits for Data Converters
- **RF/Microwave/Wireless**
  - RF Circuits and Transceivers
  - Microwave and Millimeter-Wave Circuits
  - Wireless Communication Circuits
- **Wireline**
  - High-Speed Interface
  - Wireline Link
- **Digital Circuits, Architecture, and Systems**
  - Multimedia Systems and Image Processing Applications
  - Digital Signal Processing and Communication Systems
  - Embedded Software and Systems
  - Hardware Security Circuits
  - Memory Circuits and Systems

- **Machine Learning and AI**
  - Machine Learning/AI Algorithms
  - Systems and Architectures for Machine Learning/AI
  - Machine Learning Accelerators and Circuits
  - Near-Memory and In-Memory Computation for AI
  - Neuromorphic Architectures and Processors
- **SoC Design Methodology and CAD**
  - System-Level Modeling and Design Methodology
  - Logic/High-Level Synthesis and Optimization
  - Physical Design
  - Design for Manufacturability and Reliability
  - Testing, Validation, Simulation and Verification
- **Circuits and Systems for Emerging Technologies**
  - Neuromorphic and Emerging Devices and Circuits
  - Sensory and Biomedical Circuits and Systems
  - Biomedical Circuits and Systems
  - Automotive Circuits and Systems
  - IoT/IoE Circuits and Systems
  - 3-D ICs and SoC Packages

IMPORTANT DATES

- Submission of Regular Session Full Papers and Special Session Papers: **June 24, 2022**
- Submission of Special Session and Tutorial Proposals: **June 3, 2022**
- Notification of Acceptance of Special Session and Tutorial Proposals: **June 10, 2022**
- Notification of Acceptance of Regular Session Full Papers and Special Session Papers: **August 12, 2022**
- Author Registration: **September 2, 2022**
- Early Registration: **September 2, 2022**
- Submission of Final Papers (for all accepted papers): **September 2, 2022**
- On-site Registration: **October 19-21, 2022**

PAPER SUBMISSION

A complete 2-page manuscript must be submitted electronically In PDF format (In Standard IEEE double-column format posted on the conference website). Only electronic submissions will be accepted.
Accepted papers will be submitted for inclusion into IEEE Xplore subject to meeting IEEE Xplore's scope and quality requirements.
For more information, please refer to the conference website: http://www.isocc.org

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Venue - Lakai Sandpine Resort

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